Failure analysis polishing solution FA Slurry

In the failure analysis: Polishing can be used to observe the surface details of a product or material in order to determine if there are any defects or damages.

For instance, by performing polishing, surface cracks, fatigue cracks, corrosion, oxidation and other defects can be observed, thereby determining the cause of failure.

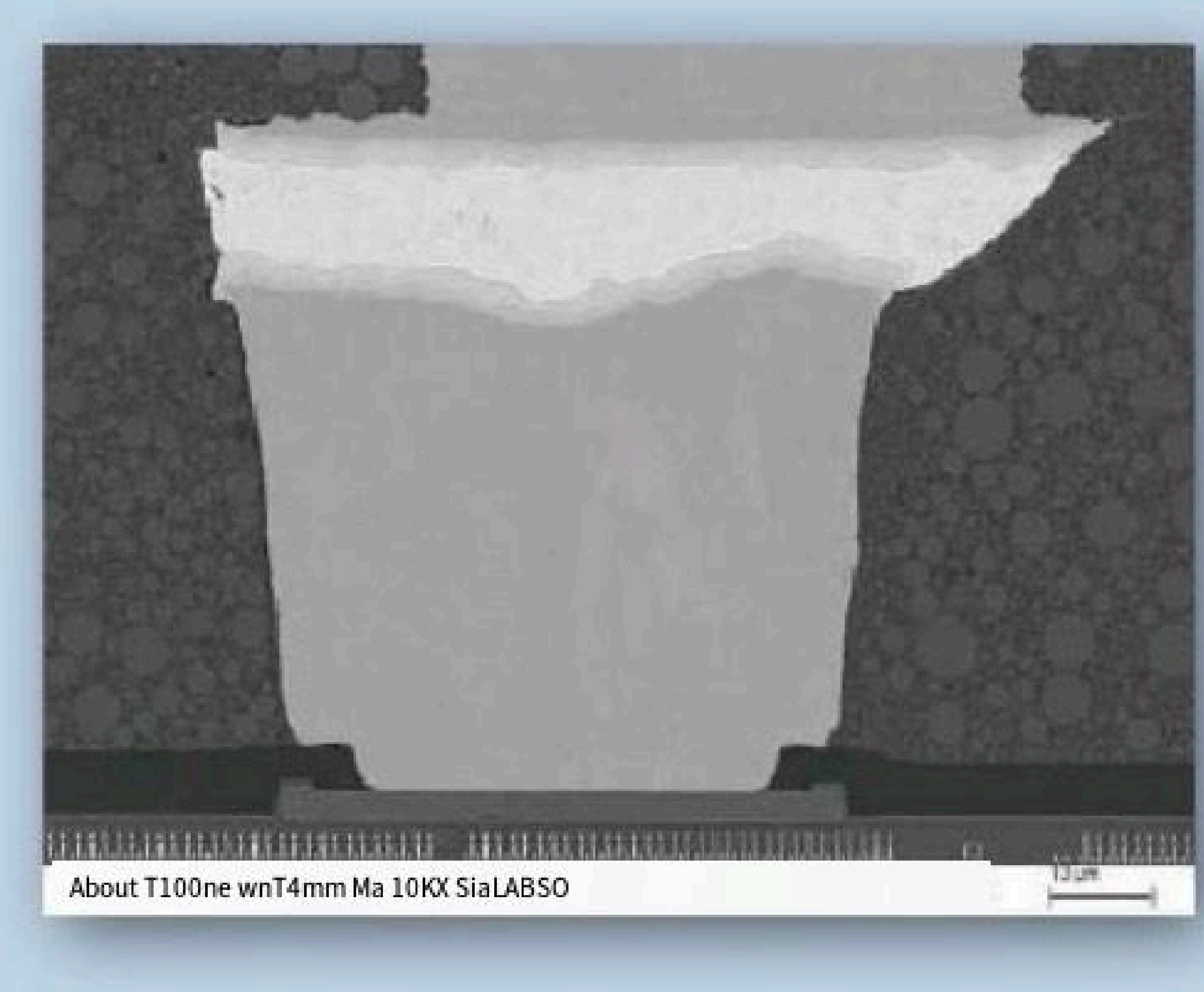
In addition, polishing can also be used to prepare samples for microscopic observation or other testing purposes.

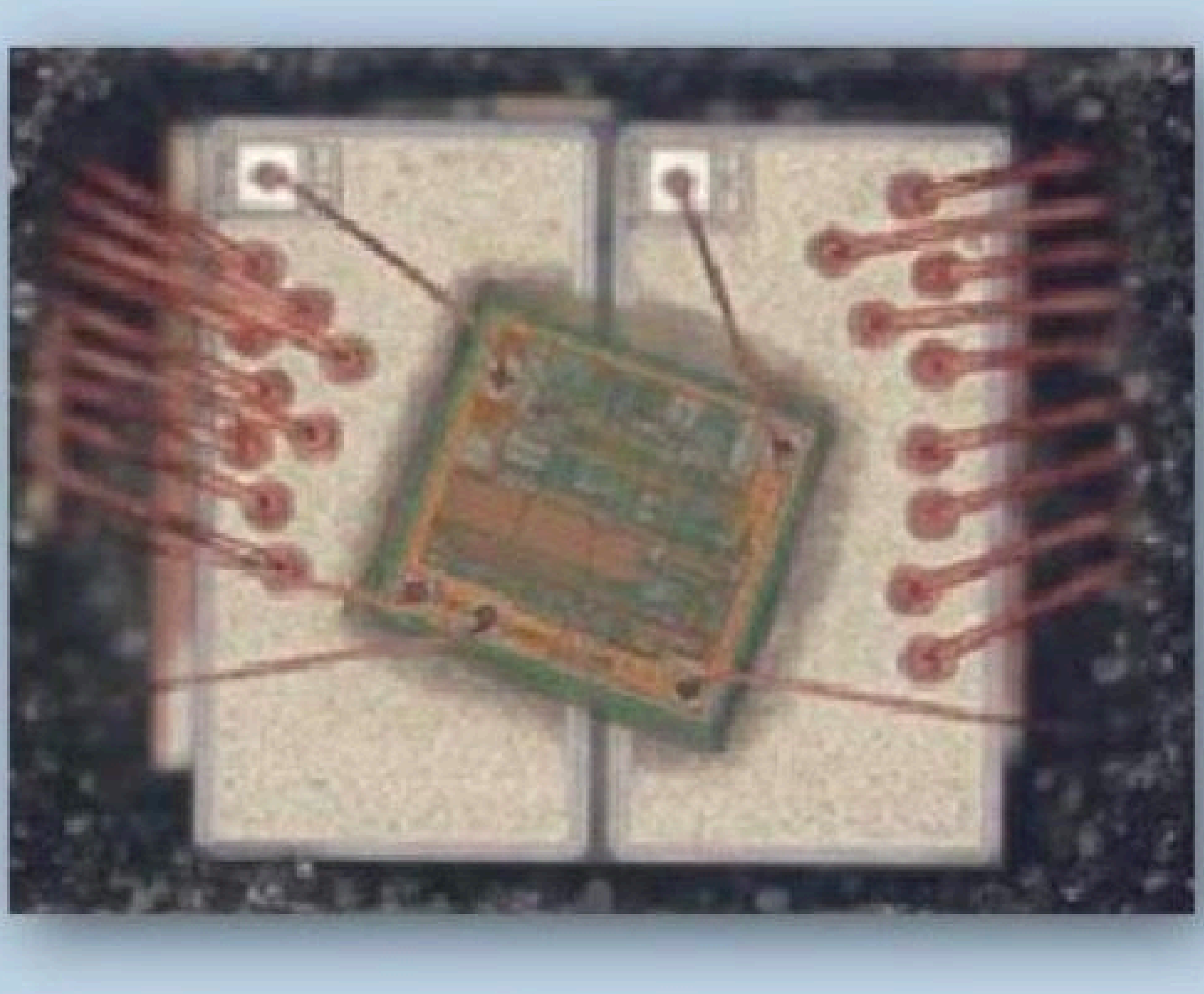
Overall, polishing is an important tool in failure analysis, which can help analysts better observe and understand the causes of product or material failure.

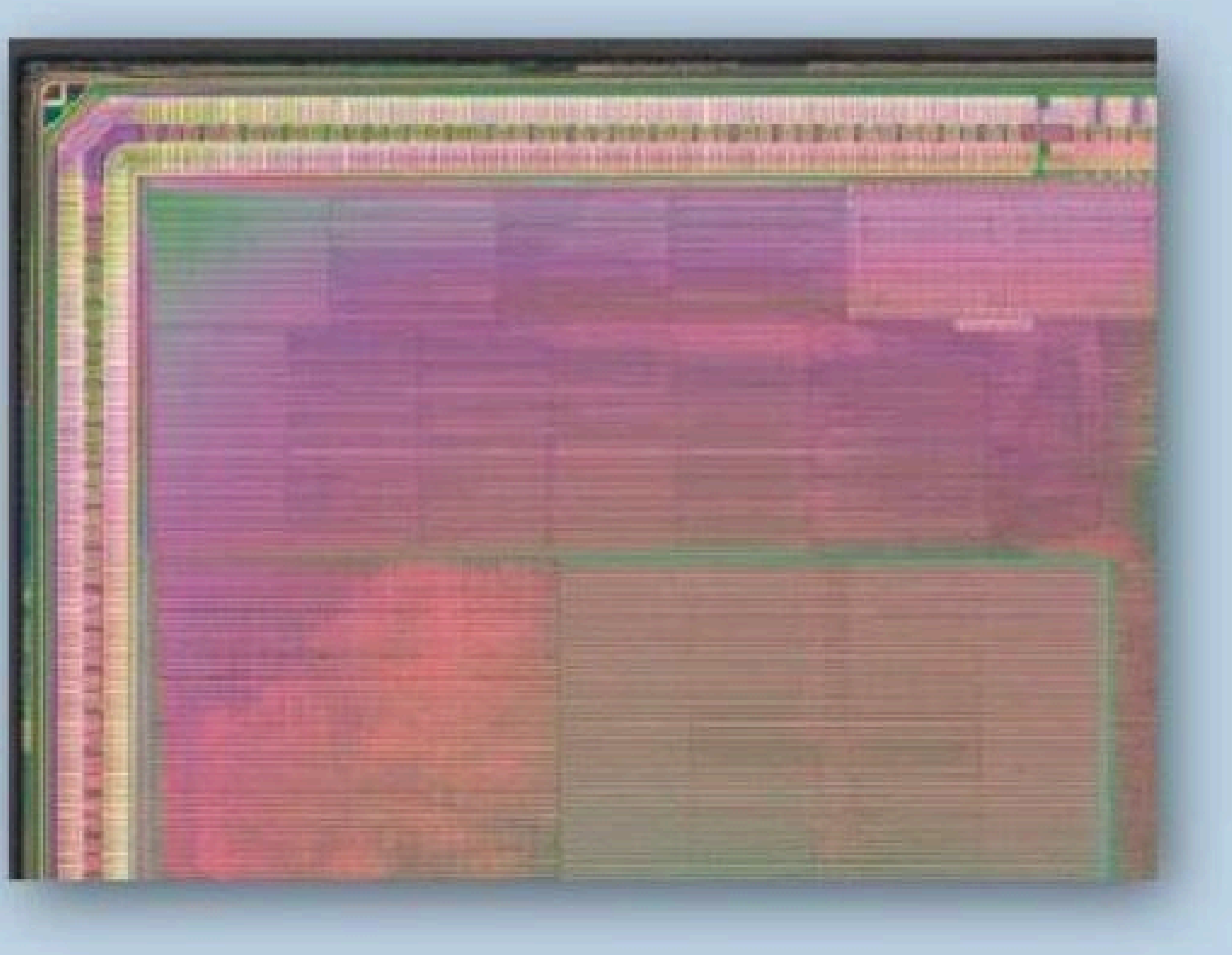
English: Perform fixed-point or non-fixed-point grinding, combined with the use of Lon Milling, to achieve a clearer cross-sectional effect.

Decap: Gold wire, copper wire, copper-plated wire, silver wire, various packages, including ultra-small packages.

Delayer: RIE can remove materials such as Oxide, Nitride, Polvimide, and Si by using plasma gases like 02, CF4, CHF3, SF6, etc. Combined with physical grinding, it can also remove layers from high-order chips and BSI samples.







Used for FA / SEM / TEM analysis, it can meet the requirements for ultra-fine surface smoothness.

The special formula can achieve final polishing for various materials, resulting in excellent mirror-like smoothness, especially for non-ferrous metals, printed circuit boards and integrated circuits.

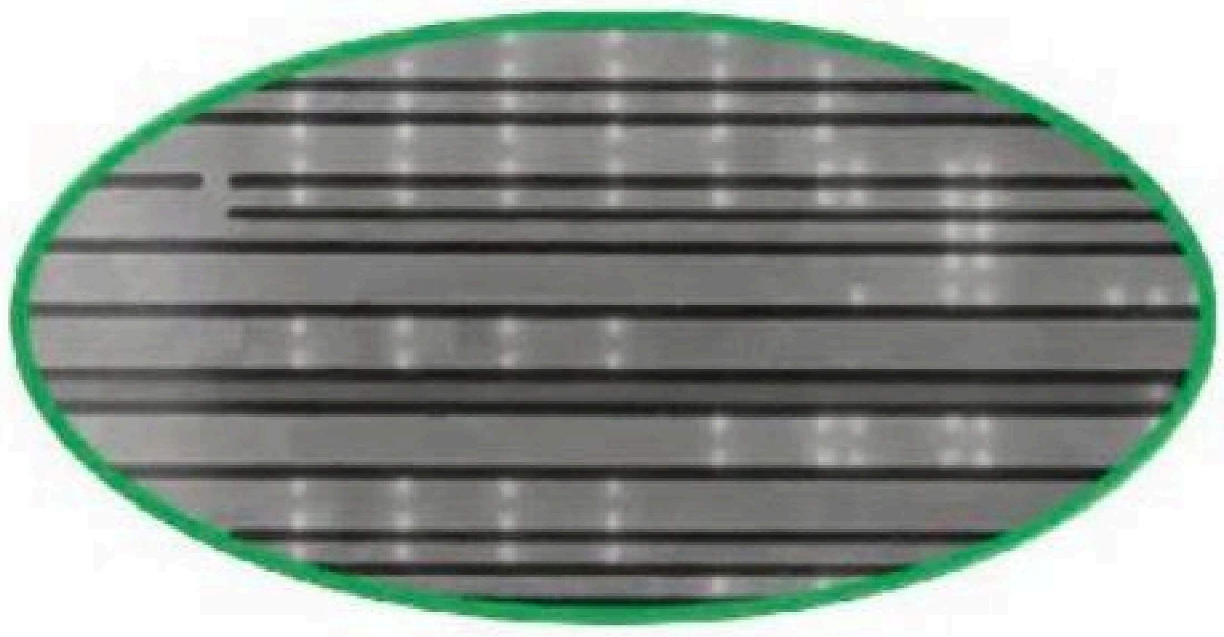
Product Inspection Report

JZ-055

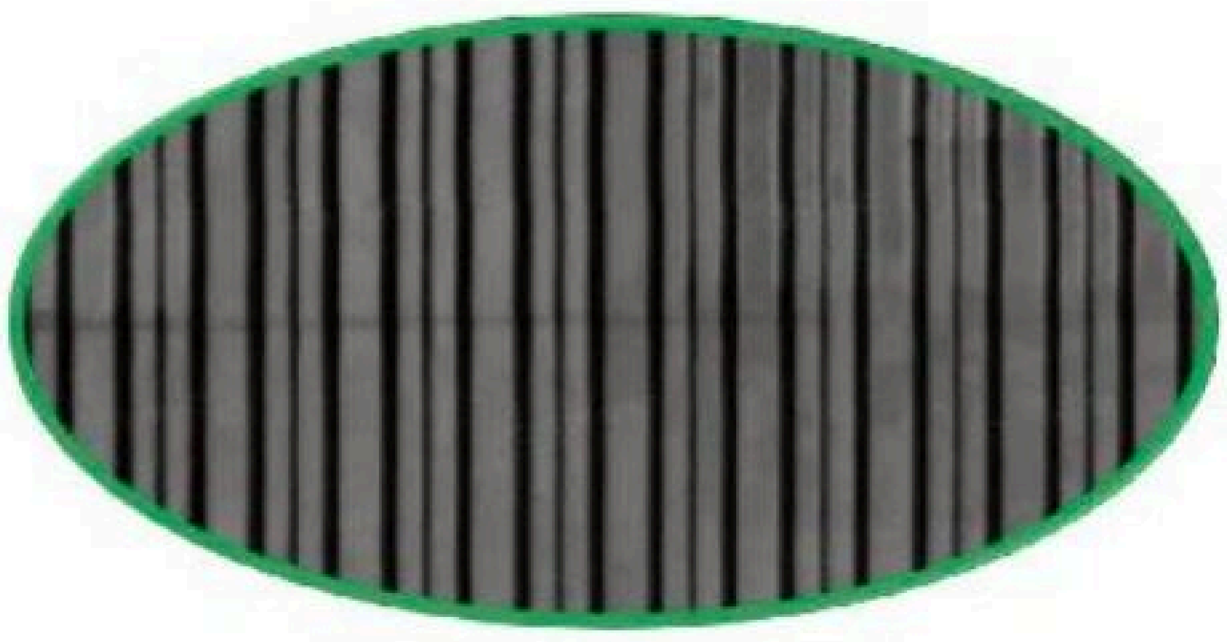
Testing items	Testing method	Measured value
Particle size (nm)	Laser particle size analyzer	80
PH (20 ℃)	pH meter	10.3
Viscosity (CP)	Viscosity meter	2.86
Density g/mL	Density meter	1.254
Nitrogen content (ppm)	Ultraviolet spectrophotometer	7.09

Our products can replace brands such as Axxxxd and Bxxxxr from abroad.

The microscopic condition of the workpiece after polishing with our polishing solution



SEM 30KV



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